

HCH100FS120E6H1

1200V/100A 6 Units SiC Hybrid Module

Description

The HCH100FS120E6H1 offer lower losses and higher energy for application such as motor drive, inverter and soft switching applications.



Features

- 1200V100 A, $V_{CE(sat)}(typ.) = 1.40V$
- Lower losses and higher energy
- Excellent short-circuit capability
- Zero Reverse Recovery from SiC Diodes

Applications

- Motor drive
- Inverter
- Welding machines
- UPS

Circuit diagram

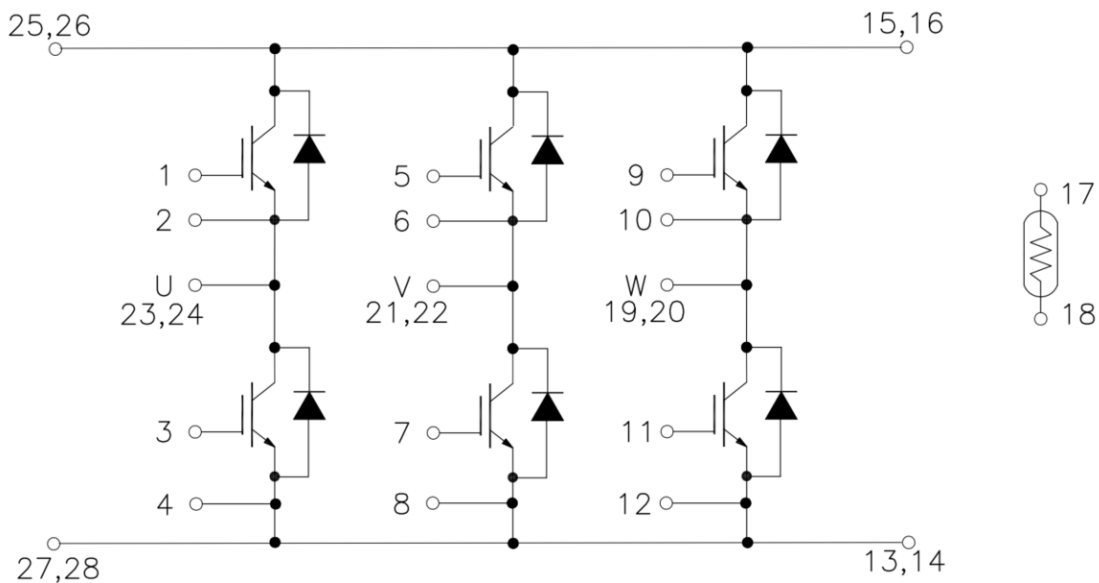


Figure 1. Out drawing & circuit diagram for HCH100FS120E6H1

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Pin Configuration and Marking Information

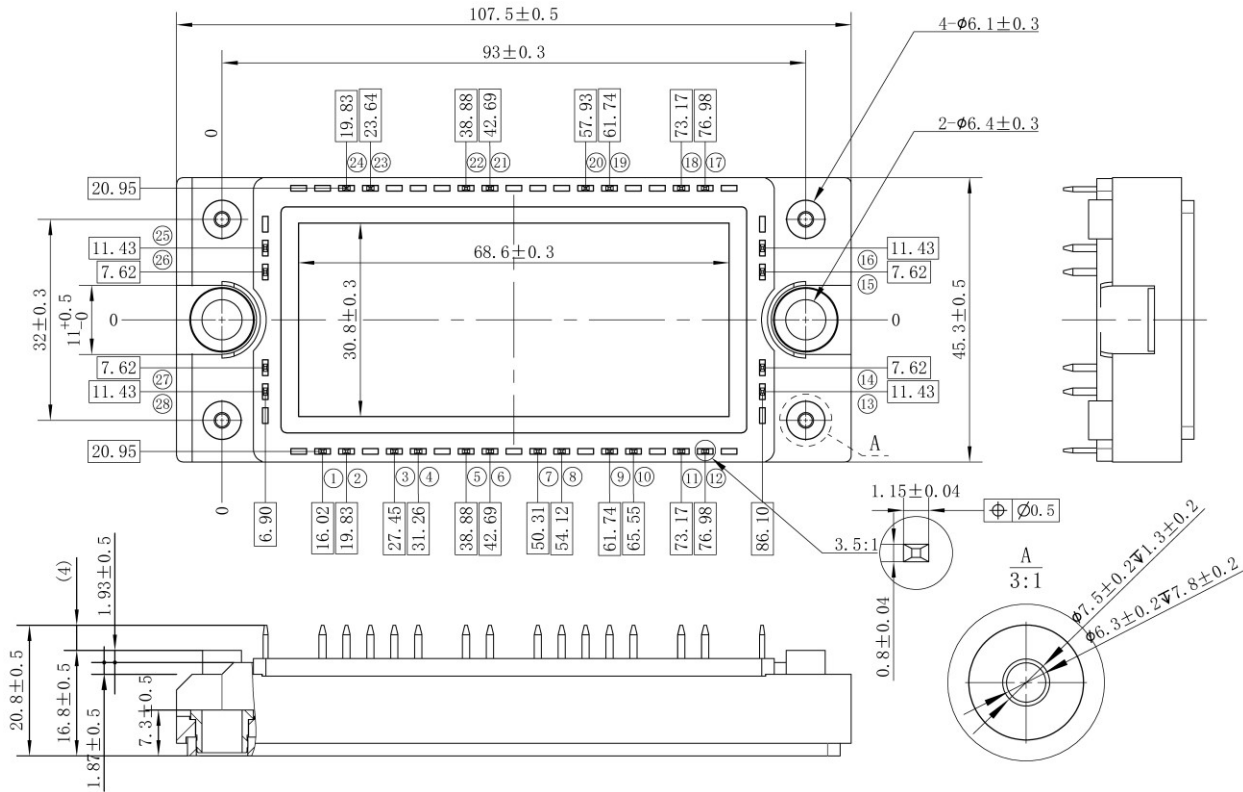


Figure 2. Pin configuration

Module

Parameter	Conditions	Value	Unit
Isolation Voltage	RMS, f = 50Hz, t = 1min	2.5	KV
CTI	-	>200	-
Module lead resistance, terminals – chip	T _c = 25°C	0.8	mΩ
Mounting torque for module mounting	M5	3.5	Nm
Weight	-	175	g

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Maximum Ratings ($T_j=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Ratings	Unit
V_{CES}	Collector-Emitter Voltage	G-E Short	1200	V
V_{GES}	Gate-Emitter Voltage	C-E Short	$\pm 20\text{V}$	V
I_C	DC Continuous Collector Current	$T_C=120^\circ\text{C}$, $T_{vjop}=150^\circ\text{C}$ (IGBT)	100	A
I_{CM}	Pulse Collector Current	$t_p=1\text{ms}$, Note1	200	A
P_C	Maximum Power Dissipation	$T_C=25^\circ\text{C}$, $T_{vjop}=150^\circ\text{C}$ (IGBT)	625	W
I_F	Diode forward Current	-	100	A
I_{FRM}	Repetitive peak forward Current	$t_p=1\text{ms}$, Note1	200	A
t_{sc}	Short Circuit Withstand Time	$V_{GE}=15\text{V}$, $V_{CE}=600\text{V}$	10	μs
T_{jmax}	Max junction temperature	-	175	$^\circ\text{C}$
T_{vjop}	Operating junction temperature	-	-40 to 150	$^\circ\text{C}$
T_{stg}	Storage temperature	-	-40 to 125	$^\circ\text{C}$

Note1: Pulse width limited by maximum junction temperature

NTC characteristics

Symbol	Parameter	Condition	Value			Unit
			Min.	Typ.	Max.	
R_{25}	Resistance	$T_C=25^\circ\text{C}$	-	5	-	$\text{k}\Omega$
R/R	Deviation of R100	$T_C=100^\circ\text{C}$, $R_{100}=493\Omega$	-5	-	5	%
P_{25}	Power dissipation	$T_C=25^\circ\text{C}$	-	-	20	mW
$B_{25/50}$	B-value	$R_2 = R_{25} \exp [B_{25/50}(1/T_2 - 1/(298,15 \text{ K}))]$	-	3375	-	K
$B_{25/80}$	B-value	$R_2 = R_{25} \exp [B_{25/80}(1/T_2 - 1/(298,15 \text{ K}))]$	-	3411	-	K
$B_{25/100}$	B-value	$R_2 = R_{25} \exp [B_{25/100}(1/T_2 - 1/(298,15 \text{ K}))]$	-	3433	-	K

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IGBT Electrical characteristics ($T_j=25^\circ\text{C}$ unless otherwise specified, chip)

Symbol	Item	Condition	Value			Unit	
			Min.	Typ.	Max.		
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C=100\text{A}$ $V_{GE}=15\text{V}$	$T_j=25^\circ\text{C}$	-	1.30	-	V
			$T_j=125^\circ\text{C}$	-	1.42	-	V
			$T_j=150^\circ\text{C}$	-	1.45	-	V
			$T_j=175^\circ\text{C}$	-	1.50	-	V
$V_{GE(th)}$	Gate-Emitter threshold Voltage	$I_C=5.7\text{mA}$, $V_{CE}=V_{GE}$	5.0	5.8	6.5	V	
Q_G	Gate charge	$V_{GE} = -15\text{V to } +15\text{V}$	-	1728	-	nC	
R_{Gint}	Internal gate resistor	-	$T_j=25^\circ\text{C}$	-	2.1	-	Ω
C_{ies}	Input Capacitance	$V_{CE}=25\text{V}$	$T_j=25^\circ\text{C}$	-	21.6	-	nF
C_{oes}	Output Capacitance	$V_{GE}=0\text{V}$		-	0.59	-	nF
C_{res}	Reverse transfer Capacitance	$f=1\text{MHz}$		-	0.17	-	nF
I_{CES}	Collector- Emitter Cut off Current	$V_{CE}=1200\text{V}$, $V_{GE}=0\text{V}$	$T_j=25^\circ\text{C}$	-	-	1	mA
I_{GES}	Gate-Emitter Leakage Current	$V_{GE}=20\text{V}$, $V_{CE}=0\text{V}$	$T_j=25^\circ\text{C}$	-	-	1	μA
$t_{d(on)}$	Turn-on delay time	$V_{CC}=600\text{V}$ $I_C=100\text{A}$ $V_{GE}=+15\text{V}/-8\text{V}$ $R_{Gon} = R_{Goff}=4.7\Omega$ Inductive load	$T_j=25^\circ\text{C}$	-	212	-	ns
			$T_j=125^\circ\text{C}$	-	210	-	
			$T_j=150^\circ\text{C}$	-	209	-	
t_r	Rise time		$T_j=25^\circ\text{C}$	-	22	-	ns
			$T_j=125^\circ\text{C}$	-	33	-	
			$T_j=150^\circ\text{C}$	-	37	-	
$t_{d(off)}$	Turn-off delay time		$T_j=25^\circ\text{C}$	-	457	-	ns
			$T_j=125^\circ\text{C}$	-	532	-	
			$T_j=150^\circ\text{C}$	-	549	-	
t_f	Fall time	$T_j=25^\circ\text{C}$	-	216	-	ns	
		$T_j=125^\circ\text{C}$	-	348	-		
		$T_j=150^\circ\text{C}$	-	401	-		
E_{on}	Turn-on power dissipation	$T_j=25^\circ\text{C}$	-	3.99	-	mJ	
		$T_j=125^\circ\text{C}$	-	5.34	-		
		$T_j=150^\circ\text{C}$	-	5.70	-		
E_{off}	Turn-off power dissipation	$T_j=25^\circ\text{C}$	-	10.21	-	mJ	
		$T_j=125^\circ\text{C}$	-	14.23	-		
		$T_j=150^\circ\text{C}$	-	15.27	-		
$R_{th(j-c)}$	Thermal Resistance, Junction to Case (IGBT)		-	0.20	-	K/W	
$R_{th(c-s)}$	Thermal Resistance, Case to sink (Conductive Grease applied)		-	0.05	-	K/W	

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SiC SBDElectrical characteristics ($T_j=25^\circ\text{C}$ unless otherwise specified, chip)

Symbol	Item	Condition	Value			Unit	
			Min.	Typ.	Max.		
V_F	Diode Forward Voltage	$I_F=100\text{A}, V_{GE}=0\text{V}$	$T_j=25^\circ\text{C}$	-	1.65	-	V
			$T_j=125^\circ\text{C}$	-	2.15	-	
			$T_j=150^\circ\text{C}$	-	2.35	-	
			$T_j=175^\circ\text{C}$	-	2.55	-	
t_{rr}	Diode Reverse Recovery Time	(Switch side) $V_{CC}=600\text{V}, I_c=100\text{A}$ $V_{GE}=+15\text{V}/-8\text{V}$	$T_j=25^\circ\text{C}$	-	22	-	ns
			$T_j=125^\circ\text{C}$	-	33	-	
			$T_j=150^\circ\text{C}$	-	32	-	
Q_{rr}	Recovered charge	$R_{Gon} = R_{Goff} = 4.7 \Omega$ (SiC SBD side) $V_{rr}=600\text{V}, I_F=100\text{A}$	$T_j=25^\circ\text{C}$	-	0.597	-	μC
			$T_j=125^\circ\text{C}$	-	0.444	-	
			$T_j=150^\circ\text{C}$	-	0.464	-	
E_{rr}	Reverse recovered energy	$V_{GE}=-8\text{V}$ Inductive load switching operation	$T_j=25^\circ\text{C}$	-	0.195	-	mJ
			$T_j=125^\circ\text{C}$	-	0.114	-	
			$T_j=150^\circ\text{C}$	-	0.104	-	
$R_{th(j-c)}$	Thermal Resistance, Junction to Case (SiC SBD)		-	0.45	-	K/W	
$R_{th(c-s)}$	Thermal Resistance, Case to sink (Conductive Grease applied)		-	0.05	-	K/W	

Test Conditions

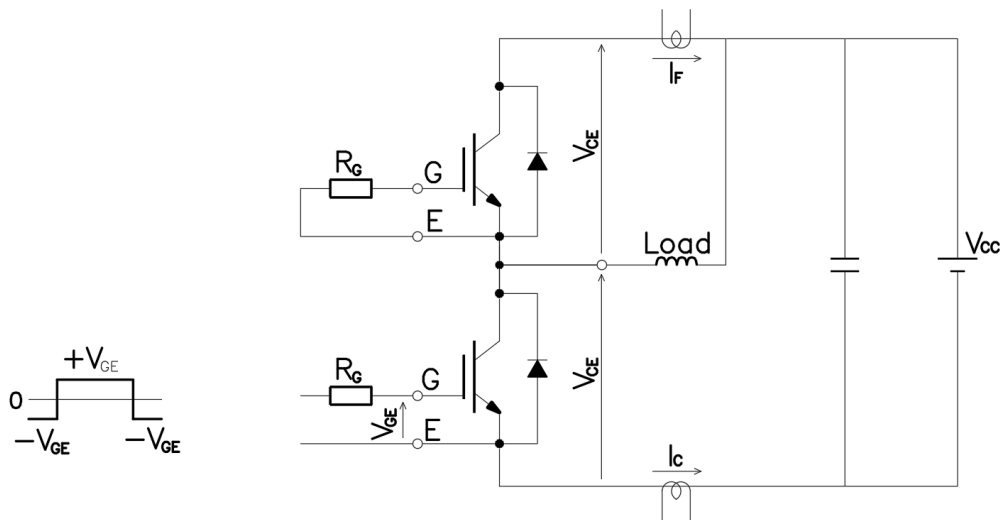


Figure 3. Switching time measure circuit

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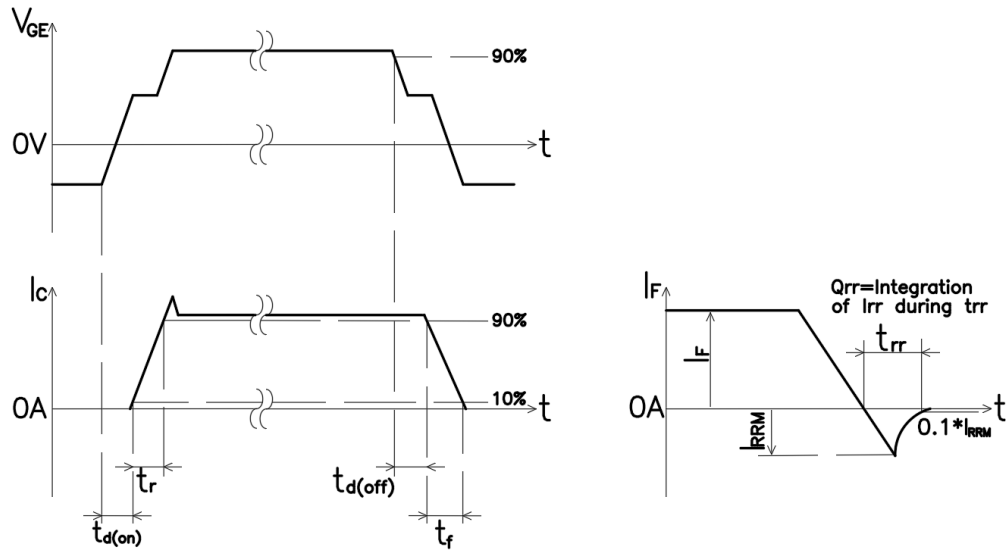
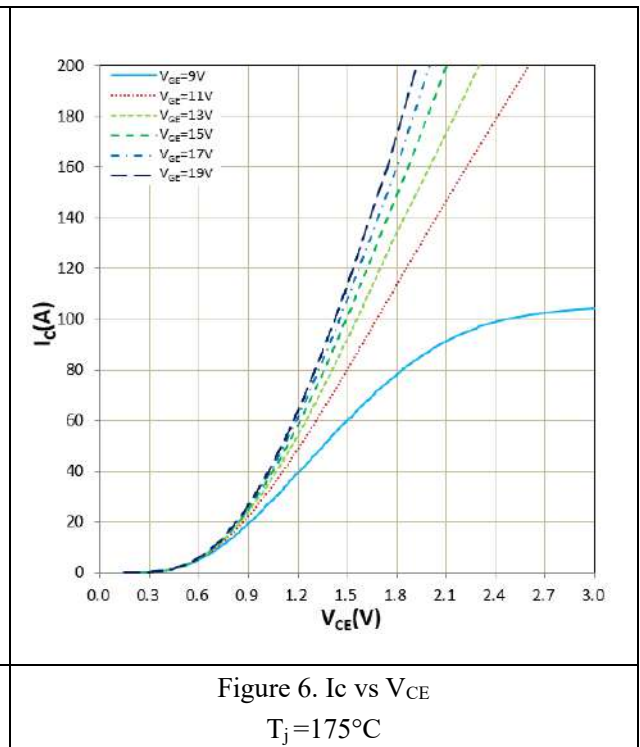
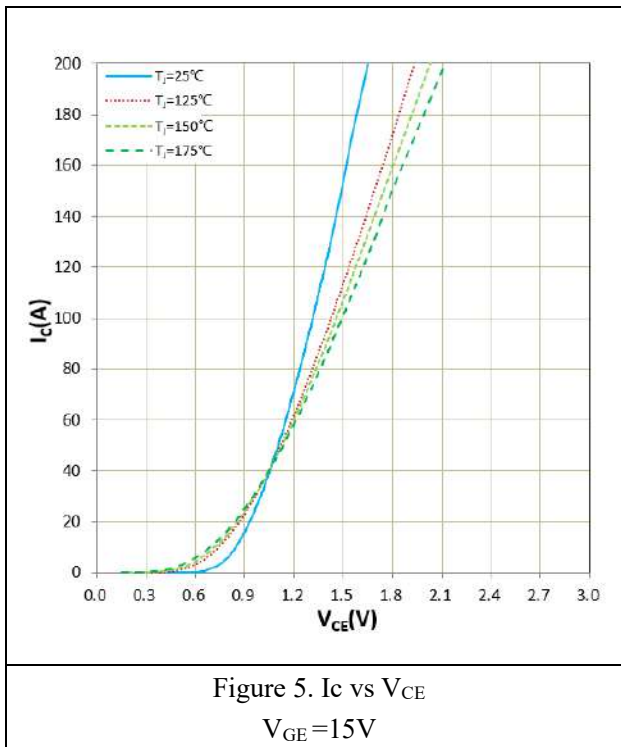
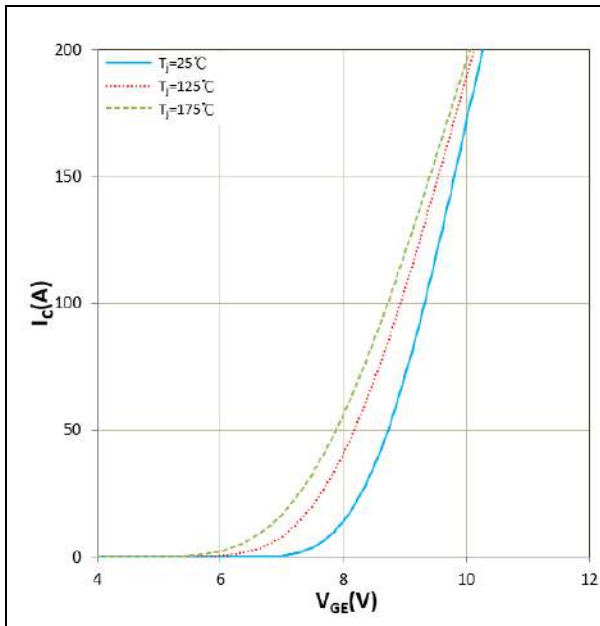
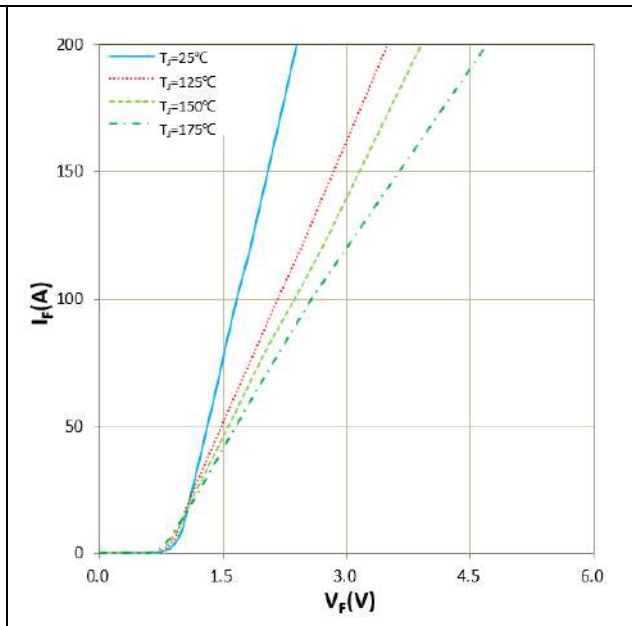
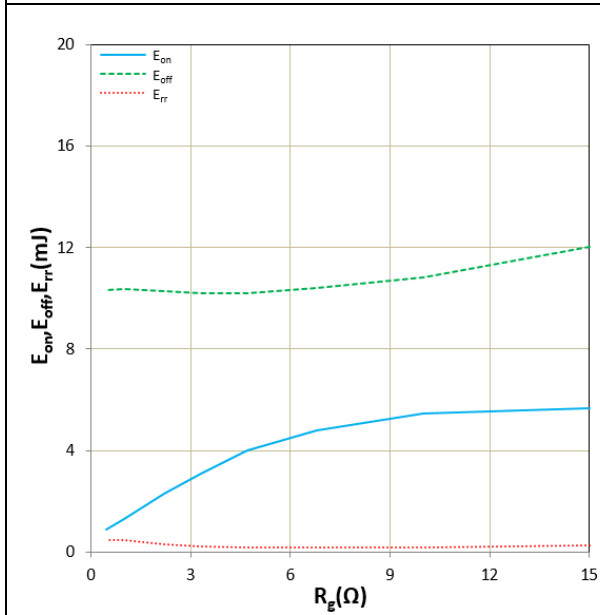
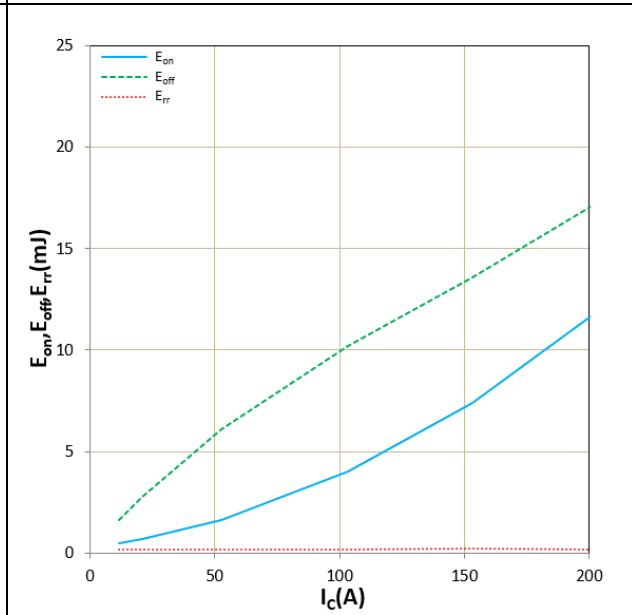


Figure 4. Switching time definition



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 Figure 7. I_c vs V_{GE}
 $V_{CE} = 20V$

 Figure 8. I_f vs V_F

 Figure 9. E_{on} , E_{off} , E_{rr} vs R_g (Typ)
 $V_{CC} = 600V$, $V_{GE} = +15V/-8V$, $I_c = 100A$, $T_j = 25^\circ C$
 Inductive Load

 Figure 10. E_{on} , E_{off} , E_{rr} vs I_c (Typ)
 $V_{CC} = 600V$, $V_{GE} = +15V/-8V$, $R_g = 4.7\Omega$, $T_j = 25^\circ C$
 Inductive Load

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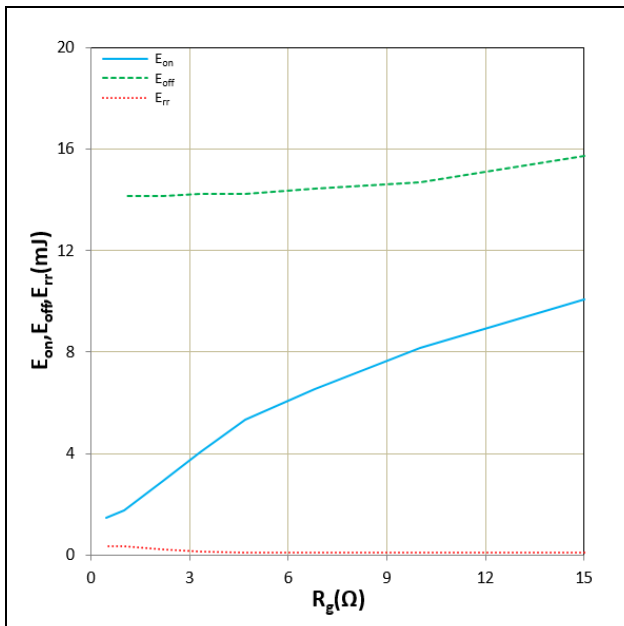


Figure 11. E_{on} , E_{off} , E_{rr} vs R_g (Typ)
 $V_{CC}=600V$, $V_{GE}=+15V/-8V$, $I_C=100A$, $T_j=125^\circ C$
 Inductive Load

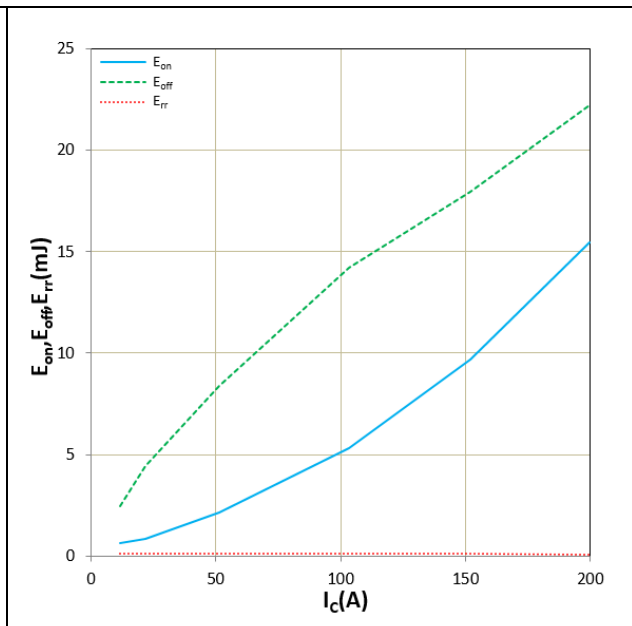


Figure 12. E_{on} , E_{off} , E_{rr} vs I_c (Typ)
 $V_{CC}=600V$, $V_{GE}=+15V/-8V$, $R_g=4.7\Omega$, $T_j=125^\circ C$
 Inductive Load

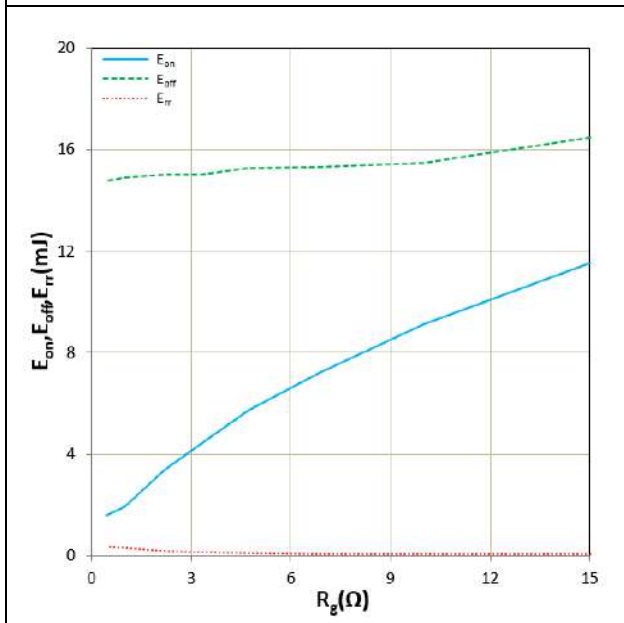


Figure 13. E_{on} , E_{off} , E_{rr} vs R_g (Typ)
 $V_{CC}=600V$, $V_{GE}=+15V/-8V$, $I_C=100A$, $T_j=150^\circ C$
 Inductive Load

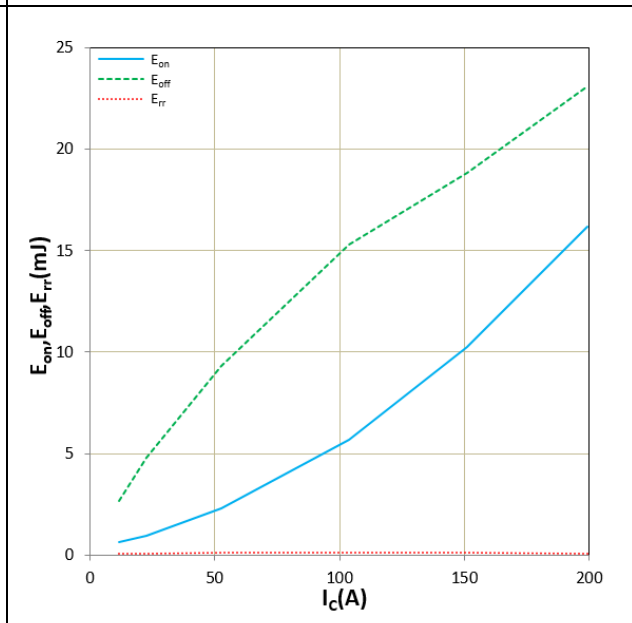


Figure 14. E_{on} , E_{off} , E_{rr} vs I_c (Typ)
 $V_{CC}=600V$, $V_{GE}=+15V/-8V$, $R_g=4.7\Omega$, $T_j=150^\circ C$
 Inductive Load

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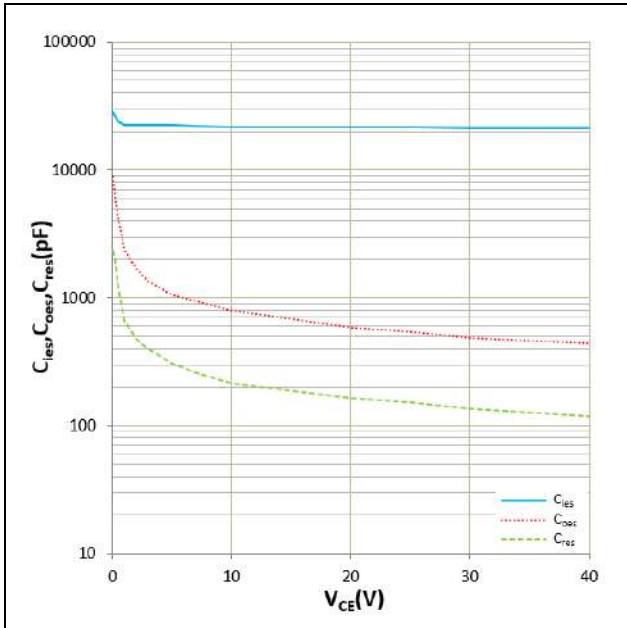


Figure 15. C_{ies} , C_{oes} , C_{res} vs V_{CE}
 $T_j = 25^\circ\text{C}$, $f = 1\text{MHz}$

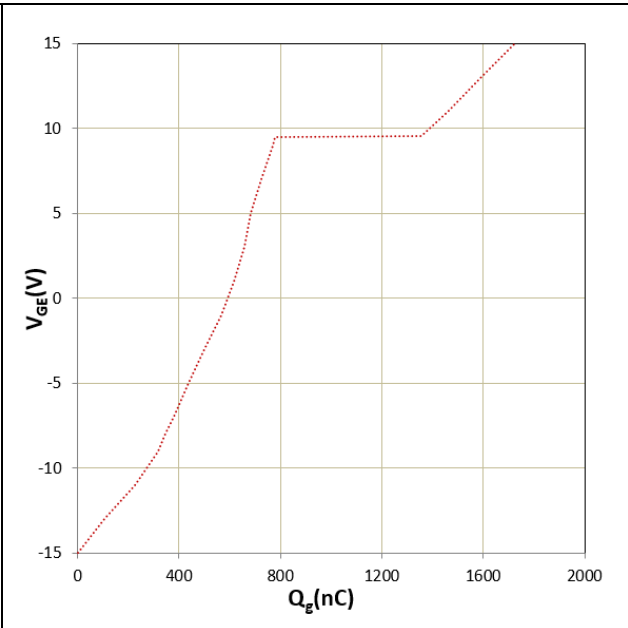


Figure 16. Gate charge
 $T_j = 25^\circ\text{C}$

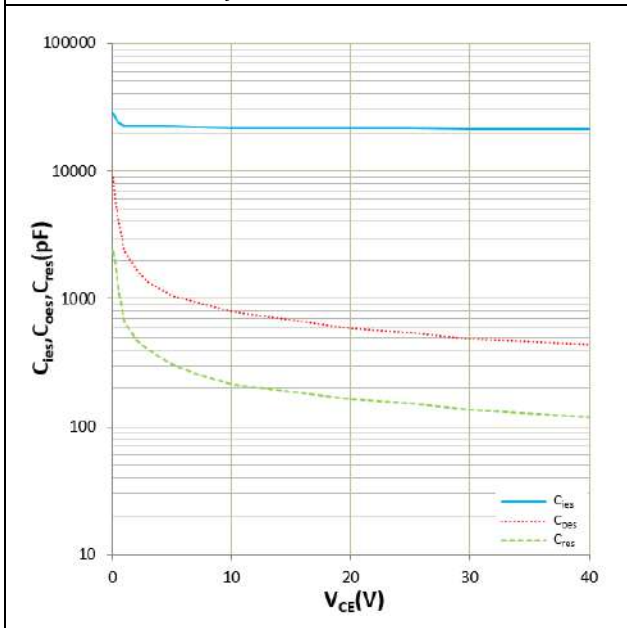


Figure 17. Transient thermal resistance

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IMPORTANT NOTICE:

This product data sheet describes the characteristics of this product for which a warranty is granted.

Any such warranty is granted exclusively under the terms and conditions of the supply agreement.

There will be no guarantee or of any kind for the product and its characteristics.

The data contained in this document is exclusively intended for technically trained staff. You and your technical departments will have to evaluate the product's suitability for the intended application and the completeness of the product data concerning such application.

Due to technical requirements, our product may contain dangerous substances.

For information on the types in question, please contact the sales staff responsible for you.

Changes to this product data sheet are reserved.

Please contact the sales staff (sales@hiitio.com) for further information on the product, technology, delivery terms, conditions and prices.

Instruction note

Naming rules for power module product models (Industrial module)

Product Model							
	HC	G	100	FF	120	E3	A
Hecheng Code							
Module type	G : IGBT module D : FRD module S : SiC module H : Si/SiC hybrid						
Current level (A)	50~900						
Topology structure	FZ : A switch unit FF : Half bridge FS : Three phase F4 : H Bridge F3L : Three level DF : Boost Circuit FD : Braking Circuit FP : Rectification+Inverter+Control move AL : ANPC CL : Chopper						
Voltage level (x10) (V)	650~2200						
Packaging form+features (A...Z)	A1: 34 mm A2: 62 mm D0: Flow0 D1: Flow1 D2: Flow2 E1: Easy 1B E2: Easy 2B E3: Econo Dual E4 : E4 E5 : ED3S E6 : EconoPIM2 E7 : EconoPIM3 E9 : ED3H F0 : F0						
Feature :A:	Special Code Nil: Standard						

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